Transaction Information

Tool ID	FIB2103
Tool Status	Disconnected
Location	Malta, USA
Wafer Size	300 mm
Fab Section	Lab
Tool Available Date	2022-04-18

General Product Information

Vendor Supplier	FEI
Model	FEI ExSolve CLM next Gen
Vintage	2015
Serial No	9923535
Asset Description	FIB2103-T-MT
Software Version	NA
CIM	Factory Automation Available
Process	Cut samples from wafers in line

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Handler System	Brooks Front End	1	
Options System	Gas Injection System (GIS) Module, C-Dep (SEM),Ins-Dep (SEM),W-Dep (SEM), W-Dep, C-Dep	5	
Main System	FEI ExSolve G2 Full Wafer TEM Preparation System	1	
Factory Interface	SMIF	1	
Others			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
TMC Vibration Isolation Table, Edwards XDS35 Dry Pumps	3	

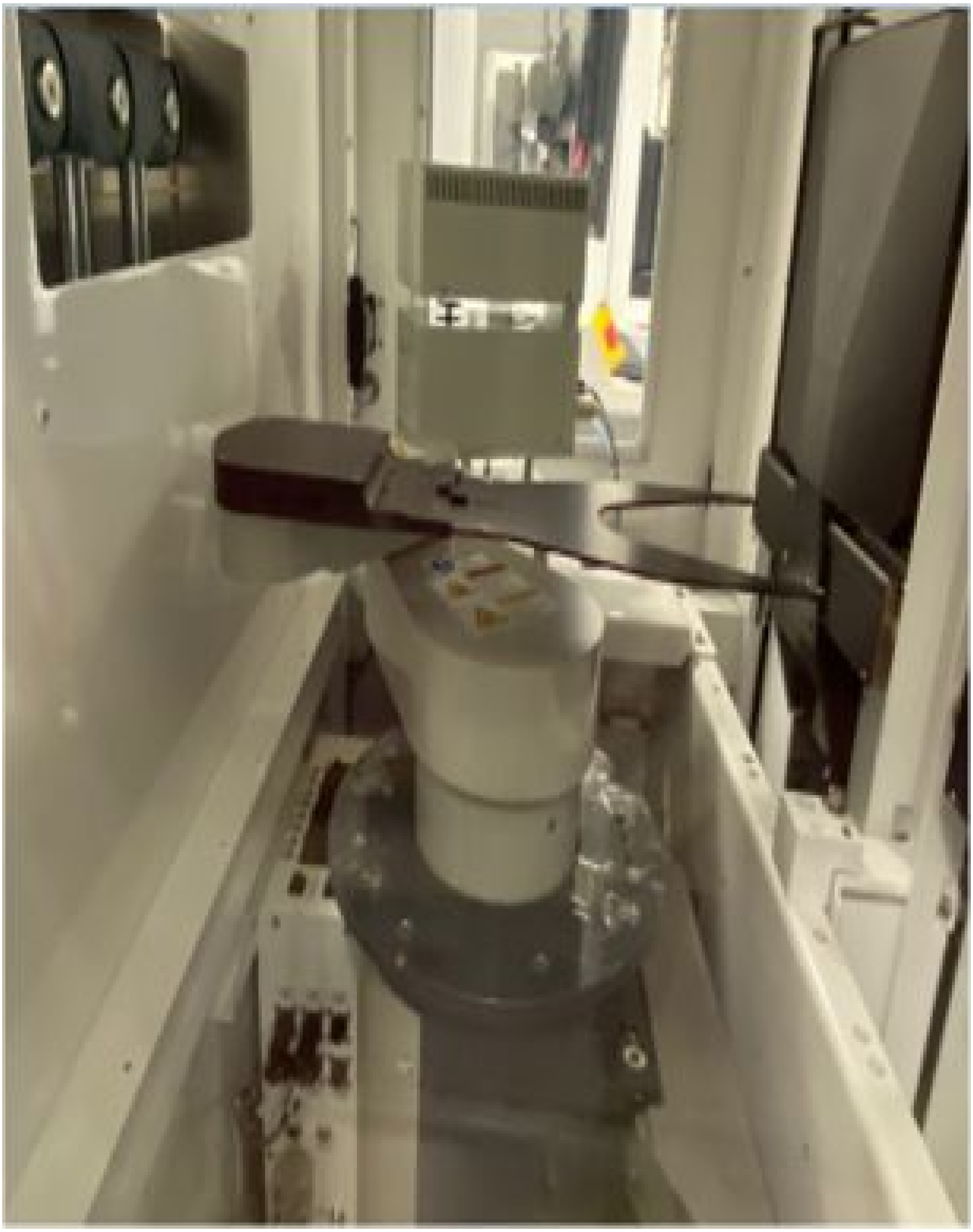
Missing/Faulty Parts / Accesorries List

Description	Quantity
Front End Flash Drive Failure, tool is down	1

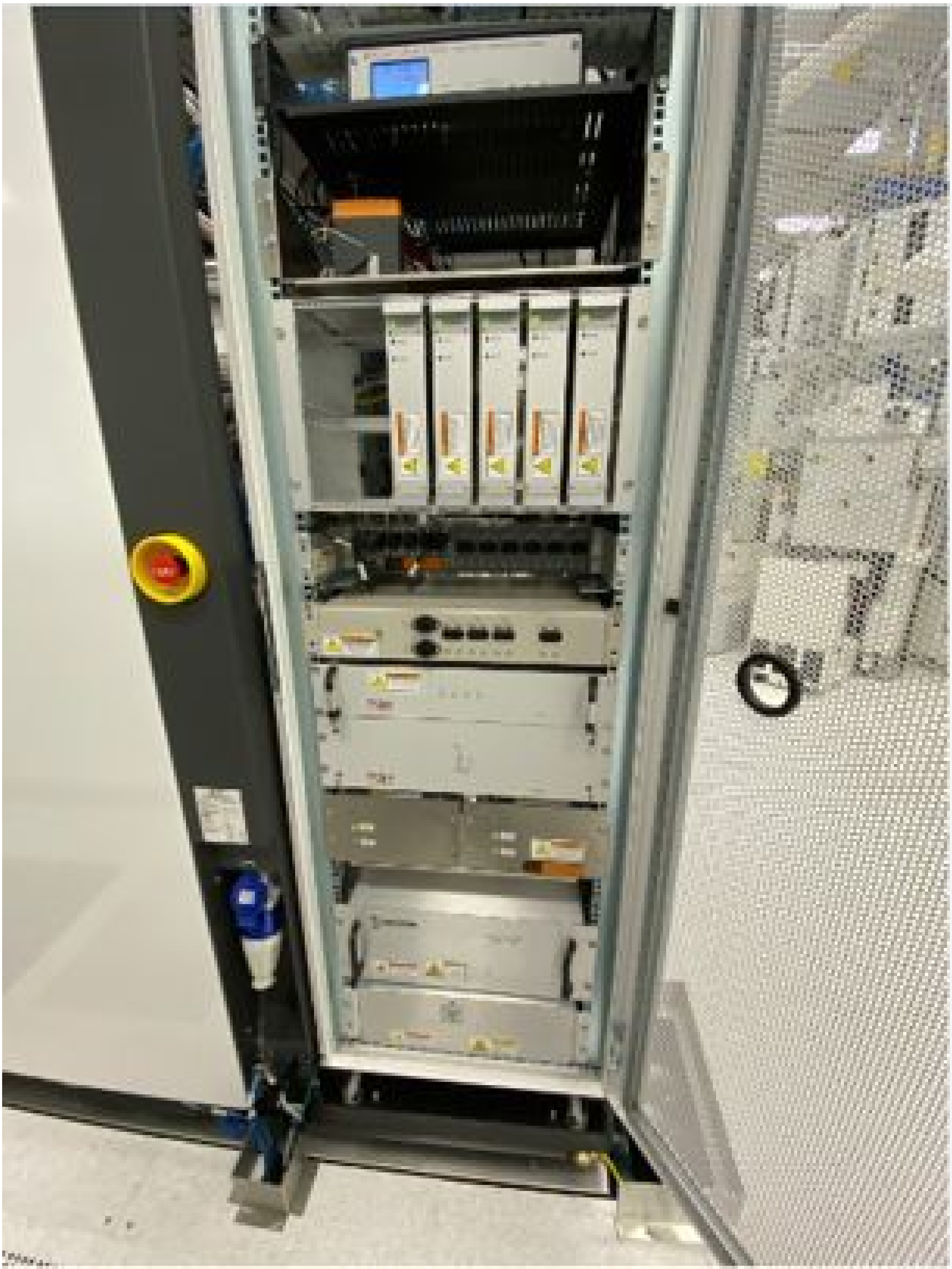
Tool Pictures

General	FEI ExSolve G2 Full Wafer TEM Preparation System

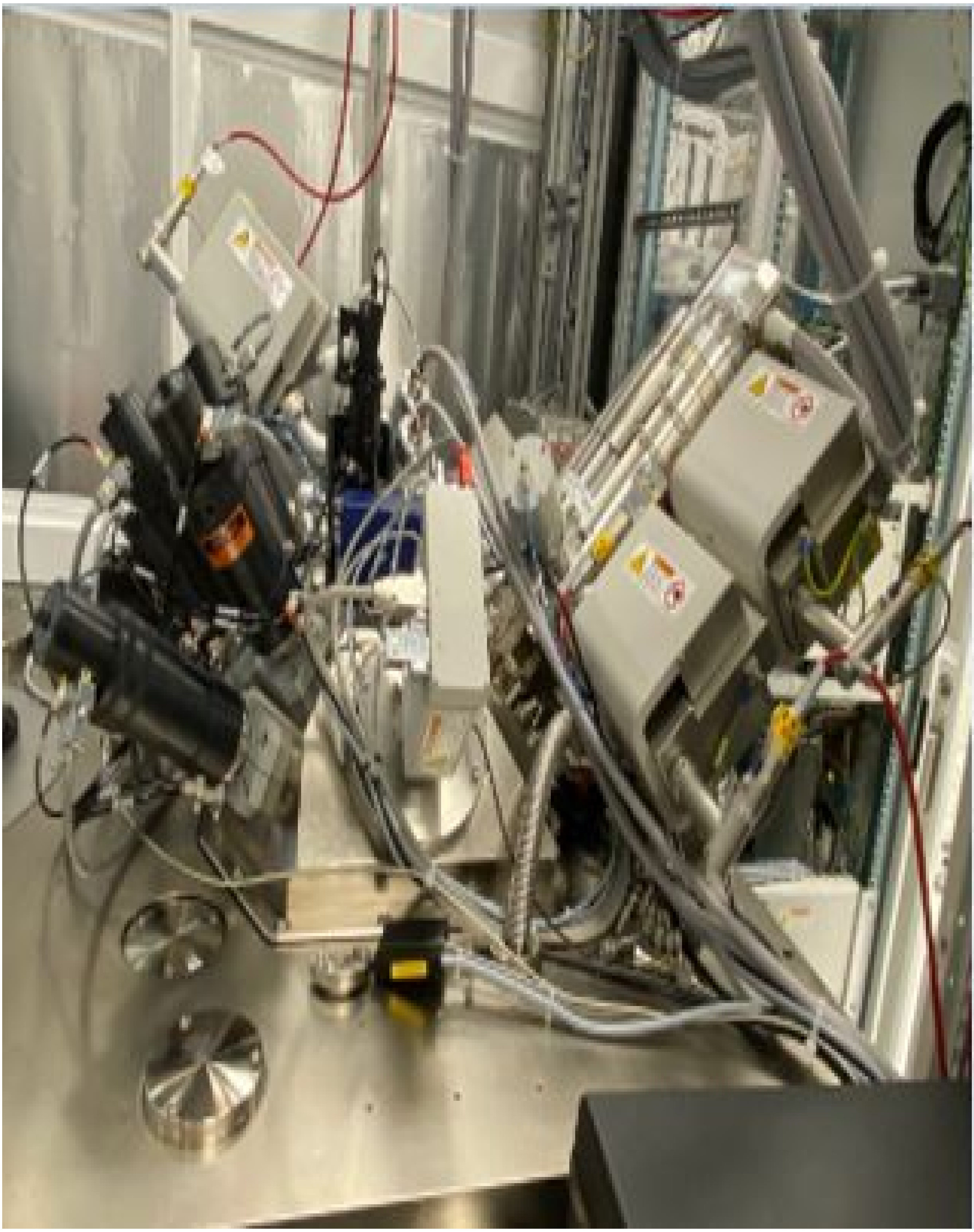
Hardware Fab	SMIF, Brooks Front End



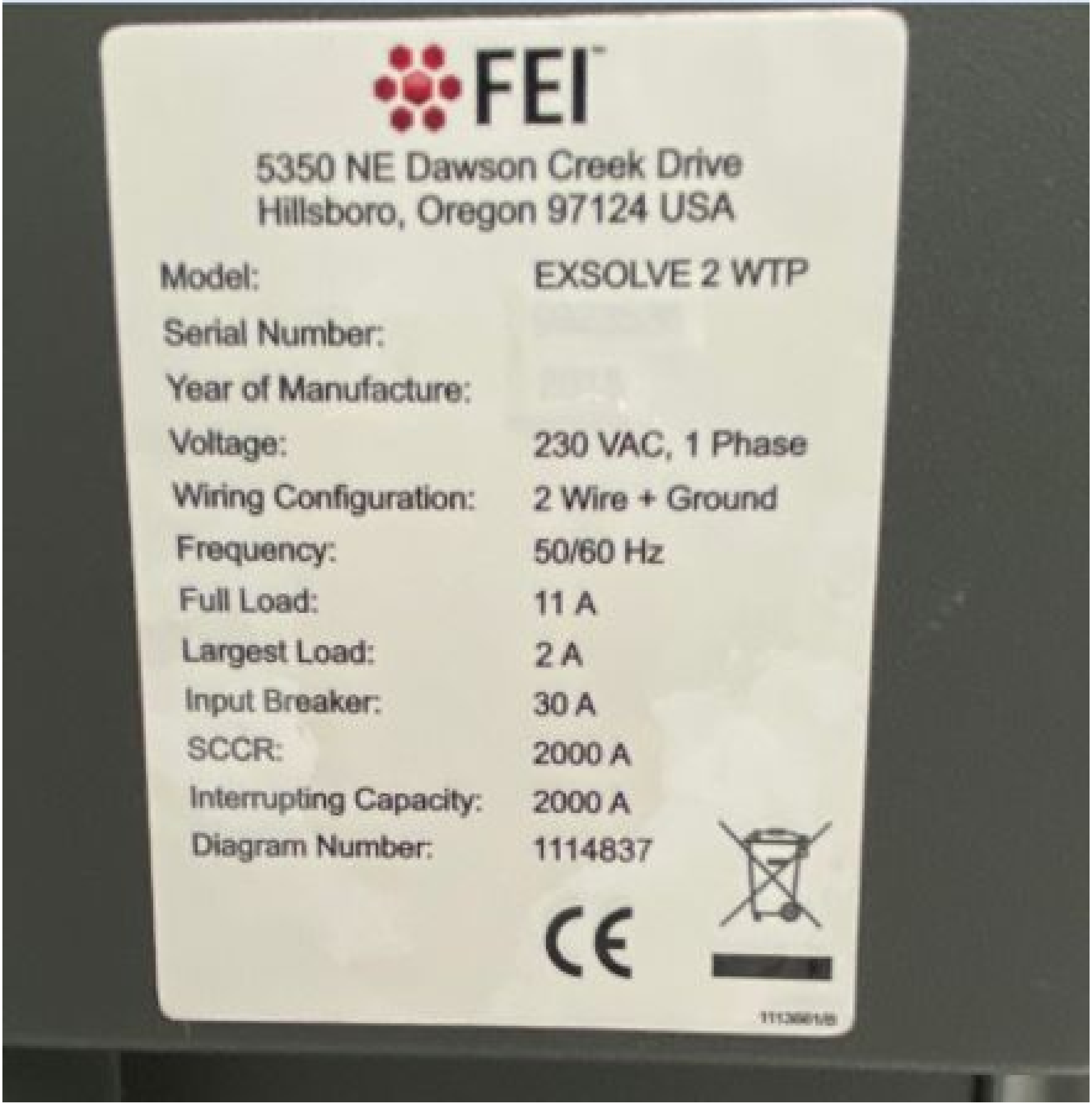
Hardware Fab	SMIF, Brooks Front End



Hardware Sub-fab	SEM, Dep



Manufacture Serial	9923535



FEI

5350 NE Dawson Creek Drive
Hillsboro, Oregon 97124 USA

Model:	EXSOLVE 2 WTP
Serial Number:	[redacted]
Year of Manufacture:	[redacted]
Voltage:	230 VAC, 1 Phase
Wiring Configuration:	2 Wire + Ground
Frequency:	50/60 Hz
Full Load:	11 A
Largest Load:	2 A
Input Breaker:	30 A
SCCR:	2000 A
Interrupting Capacity:	2000 A
Diagram Number:	1114837

Additional Tool Data Files